

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. - 16. (Canceled)

(9, 10, 11)

17. (New) An apparatus for processing a substrate, comprising:

a) an indexer portion comprising

A1 a downside structure comprising a transfer robot for transferring a substrate from/to a carrier capable to hold a plurality of substrates, and

an upside structure defined above said downside structure and comprising an inspection section operable to inspect said substrate; and

b) a processing portion comprising

an arrangement of processing units for applying a series of processing to said substrate transferred from said transfer robot, and

a transport robot for transporting said substrate between said arrangement of processing units, wherein

a plane area of said upside structure projected onto a horizontal plane is included in a plane area of said downside structure projected onto said horizontal plan, and wherein

said upside structure is provided in a location out of a range in which said transfer robot moves for transferring substrate between said carrier and said processing portion.

13 18. (New) The apparatus in accordance with claim 17, wherein

said inspection section comprises a plurality of inspection units horizontally separated with each other across a gap space, and

said transport robot is operable to access to each inspection unit from said gap space.

15 19. (New) The apparatus in accordance with claim 17, wherein

said inspection section includes at least one of:

a resist thickness measurement unit for measuring thickness of resist formed on said substrate;

a pattern line width measurement unit for measuring line width of lines formed on said substrate;

a pattern superposition measurement for measuring superposition of circuit patterns formed on said substrate; and

a macro defect inspection for detecting macro defect on said substrate.

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20. (New) The apparatus in accordance with claim 17, wherein said inspection section includes

a complex inspection unit for measuring thickness of resist formed on said substrate, line width of lines formed on said substrate, and for measuring superposition of circuit patterns formed on said substrate, and

a macro defect inspection unit for detecting macro defect on said substrate.

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21. (New) An apparatus for processing a substrate, comprising:

a) an indexer portion comprising

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wnt a downside structure comprising a transfer robot for transferring a substrate from/to a carrier capable to hold a plurality of substrates, and

an upside structure defined above said downside structure and comprising an inspection section operable to inspect said substrate; and

b) a processing portion comprising

an arrangement of processing units for applying a series of processing to said substrate transferred from said transfer robot, and

a transport robot for transporting said substrate between said arrangement of processing units, wherein

a plane area of said upside structure projected onto a horizontal plane is included in a plane area of said downside structure projected onto said horizontal plane, and wherein

said downside structure comprises a carrier stage on which a plurality of carriers each containing a plurality of substrates are aligned, and

said upside structure is provided over an alignment of said plurality of substrates.

22. (New)¹³ The apparatus in accordance with claim 21, wherein
said inspection section comprises a plurality of inspection units horizontally separated
with each other across a gap space, and
said transport robot is operable to access to each inspection unit from said gap space.

23. (New)¹⁵ The apparatus in accordance with claim 21, wherein
said inspection section includes at least one of:
a resist thickness measurement unit for measuring thickness of resist formed on said
substrate;
a pattern line width measurement unit for measuring line width of lines forms on said
substrate;
a pattern superposition measurement for measuring superposition of circuit patterns
formed on said substrate; and
a macro defect inspection for detecting macro defect on said substrate.

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24. (New)¹⁶ The apparatus in accordance with claim 21, wherein
said inspection section includes
a complex inspection unit for measuring thickness of resist formed on said substrate, line
width of lines formed on said substrate, and for measuring superposition of circuit patterns
formed on said substrate, and
a macro defect inspection unit for detecting macro defect on said substrate.

25. (New)^{9,10,14} An apparatus for processing a substrate, comprising:
a) an indexer portion comprising
a downside structure comprising a transfer robot for transferring a substrate from/to a
carrier capable to hold a plurality of substrates, and
an upside structure defined above said downside structure and comprising an inspection
section operable to inspect said substrate; and
b) a processing portion comprising

an arrangement of processing units for applying a series of processing to said substrate transferred from said transfer robot, and

a transport robot for transporting said substrate between said arrangement of processing units, wherein

a plane area of said upside structure projected onto a horizontal plane is included in a plane area of said downside structure projected onto said horizontal plane, and wherein

a clean air product is provided under said inspection section to supply clean air to said downside structure.

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26. (New) The apparatus in accordance with claim 25, wherein
said inspection section comprises a plurality of inspection units horizontally separated with each other across a gap space, and
said transport robot is operable to access to each inspection unit from said gap space.

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27. (New) The apparatus in accordance with claim 25, wherein
said inspection section includes at least one of:
a resist thickness measurement unit for measuring thickness of resist formed on said substrate;
a pattern line width measurement unit for measuring line width of lines forms on said substrate;
a pattern superposition measurement for measuring superposition of circuit patterns formed on said substrate; and
a macro defect inspection for detecting macro defect on said substrate.

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28. (New) The apparatus in accordance with claim 25, wherein
said inspection section includes
a complex inspection unit for measuring thickness of resist formed on said substrate, line width of lines formed on said substrate, and for measuring superposition of circuit patterns formed on said substrate, and
a macro defect inspection unit for detecting macro defect on said substrate.